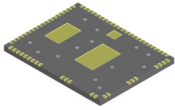
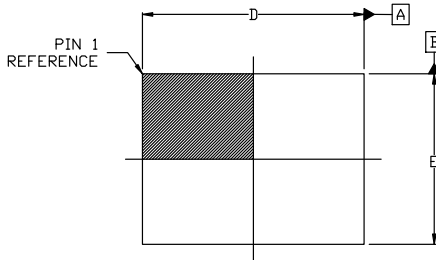


MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

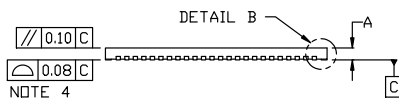


GAQFN65 13x10, 0.5P CASE 510CT ISSUE C

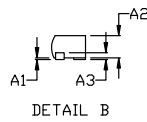
DATE 14 DEC 2021



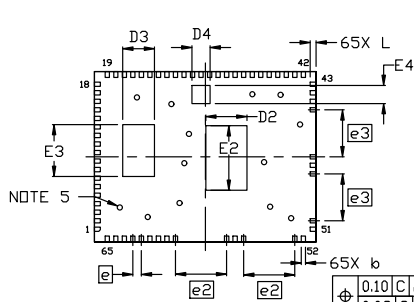
TOP VIEW



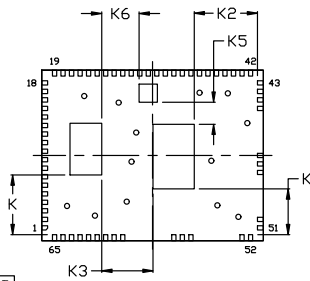
SIDE VIEW



DETAIL B



BOTTOM VIEW



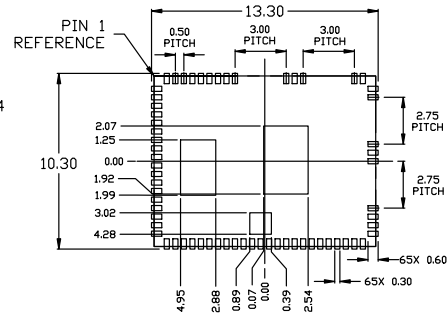
BOTTOM VIEW
(SUPPLEMENTAL)

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION *b* APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
5. 13X MOLD POST AT BOTTOM OF PACKAGE $\phi 0.3\text{mm}$ REF.

DIM	MILLIMETERS		
	MIN.	NDM.	MAX.
A	0.70	0.75	0.80
A1	0.00	---	0.05
A2	0.65 REF		
A3	0.10 REF		
<i>b</i>	0.20	0.25	0.30
D	12.90	13.00	13.10
D2	2.31	2.41	2.51
D3	1.76	1.86	1.96
D4	0.98	1.08	1.18
E	9.90	10.00	10.10
E2	3.69	3.79	3.89
E3	2.94	3.04	3.14

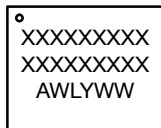
DIM	MILLIMETERS		
	MIN.	NDM.	MAX.
E4	0.96	1.06	1.16
<i>e</i>	0.50 BSC		
<i>e2</i>	3.00 BSC		
<i>e3</i>	2.75 BSC		
K	3.50 REF		
K2	3.72 REF		
K3	3.00 REF		
K4	2.68 REF		
K5	1.30 REF		
K6	2.20 REF		
L	0.25	0.35	0.45



RECOMMENDED
MOUNTING FOOTPRINT*

* For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SLDLERRM/D.

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
Y = Year
WW = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "μ", may or may not be present. Some products may not follow the Generic Marking.

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